

# MC33566

## Smart Voltage Regulator for Peripheral Card Applications

The MC33566 Low Dropout Regulator is designed for computer peripheral card applications complying with the *instantly available requirements* as specified by ACPI objectives. The MC33566 permits glitch-free transitions from “sleep” to “active” system modes and has internal logic circuitry to detect whether the system is being powered from the motherboard main 5.0 V power supply or the 3.3 V aux supply.

The MC33566 provides a regulated output voltage of 3.3 V via either an internal low dropout 5.0 V-to-3.3 V voltage regulator or an external P-channel MOSFET, depending on the operating status of the system in which the card is installed. During normal operating mode (5.0 V main supply available) the 3.3 V output is provided from the internal low dropout regulator at an output current of 0.4 A. When the motherboard enters sleep mode, the MC33566 operates from the 3.3 V aux supply and routes the aux current to the output via the external P-channel MOSFET bypass transistor controlled by the *drive out* pin. As a result, the output voltage provided to the peripheral card remains constant at 3.3 V even during host systems transitions to and from sleep mode.

### MC33566 Features:

- Output Current up to 0.4 A
- Excellent Line and Load Regulation
- Low Dropout Voltage
- Prevents Reverse Current Flow During Sleep Mode
- Glitch-Free Transfer from Sleep Mode to Active Mode
- Compatible with *Instantly Available* PC Systems

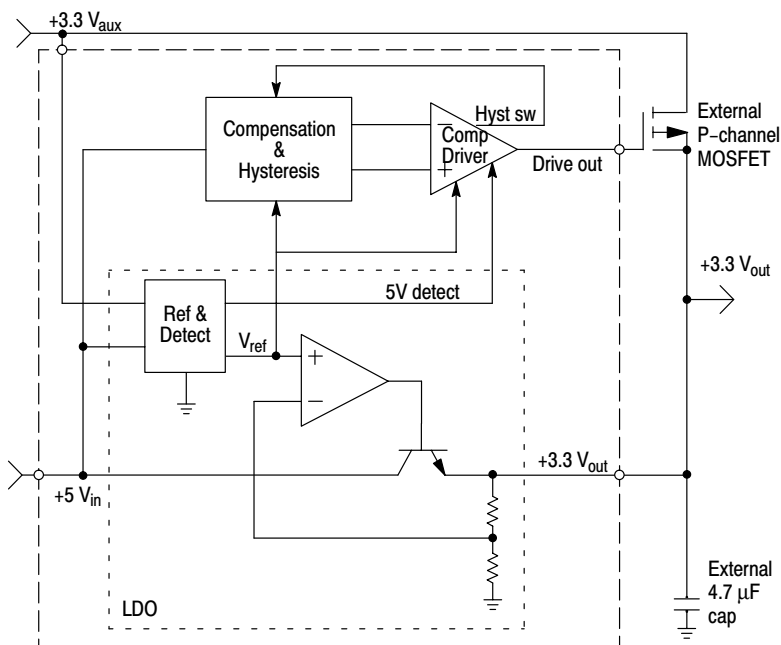


Figure 1. Simplified Block Diagram



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### MARKING DIAGRAM



Pin 1. Vaux  
2. Vin  
3. Gnd  
4. Vout  
5. Drv

Note: Tab is ground

A = Assembly Location  
WL = Wafer Lot  
Y = Year  
WW = Work Week

### ORDERING INFORMATION

Device	Package	Shipping†
MC33566D2T-1	D <sup>2</sup> PAK	50 Units/Rail
MC33566D2T-1RK	D <sup>2</sup> PAK	800 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

## PIN ASSIGNMENTS AND FUNCTIONS

Pin #	Pin Name	Pin Description
1	+3.3 V <sub>aux</sub>	Auxiliary input. Typical voltage 3.3 V.
2	+5.0 V <sub>in</sub>	This is the input supply for the IC. Typical voltage 5.0 V. (Notes 1 and 2)
3	Gnd	Logic and power ground.
4	+3.3 V <sub>out</sub>	3.3 V output provided to the application circuit (output current is sourced to this pin from the 5.0 V input.)
5	Drive out	This output drives a P-channel MOSFET with up to 2000 pF of "effective" gate capacitance. Recommended devices are the MMFT5P03HD and MTSF1P02HD. Drive out has active internal pull-up and pull-down circuitry to guarantee fast transitions.

MAXIMUM RATINGS (T<sub>C</sub> = 25°C, unless otherwise noted)

Rating	Symbol	Value	Unit
+5.0 V <sub>in</sub> Supply Voltage	V <sub>in</sub>	7.0	Vdc
	V <sub>in</sub>	−0.5 (Note 3)	Vdc
Operating Ambient Temperature	T <sub>a</sub>	−5.0 to +85	°C
Operating Junction Temperature	T <sub>J</sub>	− 5.0 to +150	°C
Lead Temperature (Soldering, 10 seconds)	T <sub>L</sub>	300	°C
Storage Temperature	T <sub>stg</sub>	− 55 to +150	°C
Package Thermal Resistance	R <sub>θJA</sub> (Note 4)	65	°C/W

## AC ELECTRICAL SPECIFICATIONS (Notes 5, 6, and 7)

Characteristic	Symbol	Min	Typ	Max	Unit
Drive High Delay (V <sub>in</sub> ramping up) C <sub>drive</sub> = 1.2 nF, measured from +5.0 V <sub>in</sub> = V <sub>thresHi</sub> to V <sub>Drive</sub> = 2.0 V	t <sub>DH</sub>	–	0.5	3.5	μS
Drive Low Delay (V <sub>in</sub> ramping down) C <sub>drive</sub> = 1.2 nF, measured from +5.0 V <sub>in</sub> = V <sub>thresLo</sub> to V <sub>Drive</sub> = 2.0 V	t <sub>DL</sub>	–	0.5	3.5	μS

1. See 5.0 V Detect Thresholds Diagram.
2. Recommended source impedance for 5.0 V supply: ≤ 0.12 Ω. This will ensure that I<sub>o</sub> × R<sub>source</sub> < V<sub>hyst</sub>, thus avoiding driveout toggling during 5.0 V detect threshold transitions.
3. V<sub>in</sub> should not be allowed to go negative relative to ground.
4. Mounted on recommended minimum PCB pad on FR4, 2-oz. copper circuit board.
5. AC specs are guaranteed by characterization, but not production tested after characterization.
6. See Figure 3. Application Block Diagram.
7. See Timing Diagram.

**DC ELECTRICAL CHARACTERISTICS** (Note 8)

Characteristic	Symbol	Min	Typ	Max	Unit
+5.0 V <sub>in</sub> Supply Voltage Range	+5.0 V <sub>in</sub>	4.35	5.0	5.5	Vdc
Reverse Leakage Current from Output	I <sub>reverse</sub>	–	–	25	μA
V <sub>aux</sub> Quiescent Current	I <sub>qaux</sub>	–	–	2.0	mA
+5.0 V <sub>in</sub> Quiescent Current, Operating	I <sub>qvin</sub>	–	–	10	mA
Load Capacitance (Note 9)	C <sub>load</sub>	4.7	22	–	μF

**REGULATOR OUTPUT**

Output Voltage (4.35 V ≤ V <sub>in</sub> ≤ 5.5 V, 0 mA ≤ I <sub>o</sub> ≤ 400 mA) T <sub>A</sub> = 25°C (T <sub>J</sub> = –5°C to 150°C)	+3.3 V <sub>out</sub>	3.267 3.234	3.30 3.30	3.333 3.366	Vdc
In-to-Out Voltage (3.9 V ≤ V <sub>in</sub> ≤ 4.35 V, V <sub>aux</sub> = 3.3 V)	V <sub>d</sub>	3.0	–	–	Vdc
Voltage Out at Max Voltage In (V <sub>in</sub> = 7.0 V)	V <sub>outmax</sub>	3.1	3.3	3.5	Vdc
Line Regulation (I <sub>o</sub> = 400 mA)	Linereg	–	–	0.4	%
Load Regulation (I <sub>o</sub> = 0 to 400 mA)	Loadreg	–	–	0.8	%

**5.0 V DETECT**

Low Threshold Voltage (+5.0 V <sub>in</sub> Falling, I <sub>o</sub> = 400 mA)	V <sub>thresLo</sub>	3.9	4.05	–	Vdc
High Threshold Voltage (+5.0 V <sub>in</sub> Rising, I <sub>o</sub> = 400 mA)	V <sub>thresHi</sub>	–	4.2	4.35	Vdc
Hysteresis	V <sub>hyst</sub>	0.05	–	–	Vdc

**DRIVE OUTPUT**

Output Peak Source Current (+5.0 V <sub>in</sub> > V <sub>thresHi</sub> )	I <sub>peak</sub>	15	–	–	mA
Output Peak Sink Current (+5.0 V <sub>in</sub> < V <sub>thresLo</sub> )	I <sub>peak</sub>	15	–	–	mA
Low Output Voltage (I <sub>oL</sub> = 200 μA, V <sub>in</sub> < V <sub>thresLo</sub> )	V <sub>oL</sub>	–	100	200	mVdc
High Output Voltage (I <sub>oH</sub> = 200 μA)	V <sub>oH</sub>	3.4	–	–	Vdc

8. –5°C < T<sub>a</sub> < 70°C, 4.35 V < V<sub>in</sub> < 5.5 V, C<sub>load</sub> ≥ 4.7 μF unless otherwise noted.

9. 4.7 μF minimum over temperature; 22 μF recommended; 500 mΩ ESR maximum.

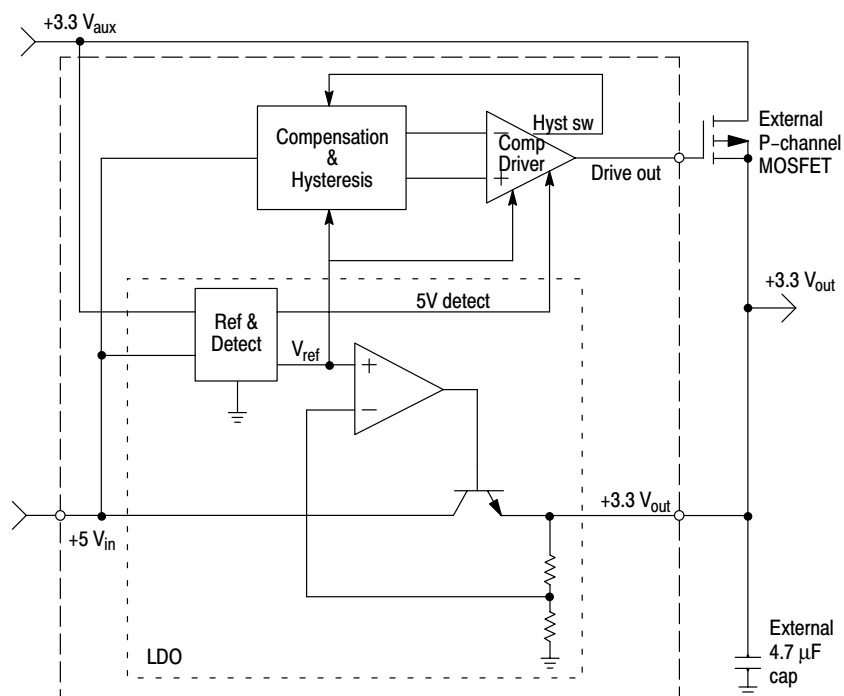


Figure 2. Functional Block Diagram

## FUNCTIONAL DESCRIPTION

**Input Blocking** – The internal NPN pass transistor of the LDO regulator ensures that no significant reverse current will flow from  $+3.3 V_{out}$  back to the  $+5.0 V_{in}$  input when the 5.0 V input is not powered and the 3.3 V<sub>in</sub> supply is present.

**5.0 Volt Detect** – Internal circuitry detects the presence of the 5.0 V input supply. When the 5.0 V supply drops below a given threshold, the  $+3.3 V_{in}$  bypass transistor (an external P-channel MOSFET) is enabled. The 5.0 V detect logic is active throughout the entire range of ramp-up from 0 to 5.5 V. Additionally, the drive out signal is never turned ON or OFF inappropriately during ramp-up of the  $+5.0 V_{in}$  supply. Also,  $+3.3 V_{out}$  never drops below 3.0 V while  $+5.0 V_{in}$  is above the 5.0 V detect minimum threshold.

**Glitch-free Transfer** – The design of the 5.0 V detect circuitry and drive out control circuitry guarantees that the  $+3.3 V_{out}$  will not exceed the output voltage specification listed in the table of DC Operating Specifications even with  $+5.0 V_{in}$  ramping up and down at the extremes of the slew rates in the table of AC Operating Specifications.

**Offset Voltage Performance** – To ensure performance when external offsets are present on the  $+5.0 V_{in}$  and  $+3.3 V_{in}$  power inputs, the device has been designed to be capable of operating with either one or both of these inputs rising from or falling to zero volts, or with offsets of 0.05 V to 0.9 V as the inputs ramp up and down.

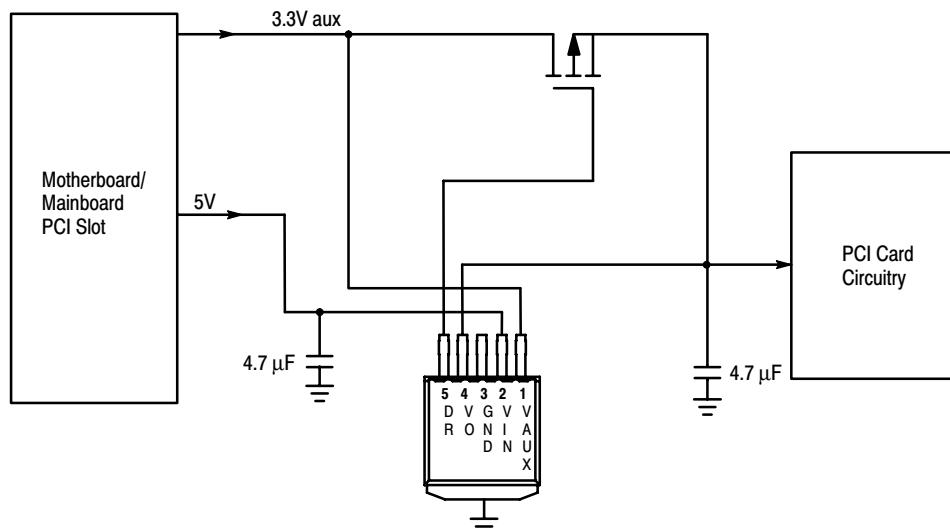
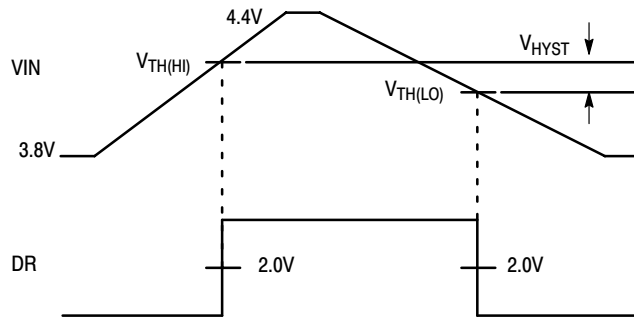


Figure 3. Application Block Diagram

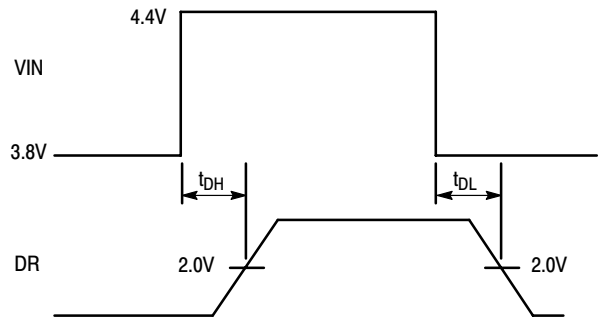
# MC33566



## NOTE:

(1)  $V_{in}$  rise and fall times (10% to 90%) to be  $\geq 100 \mu s$ .

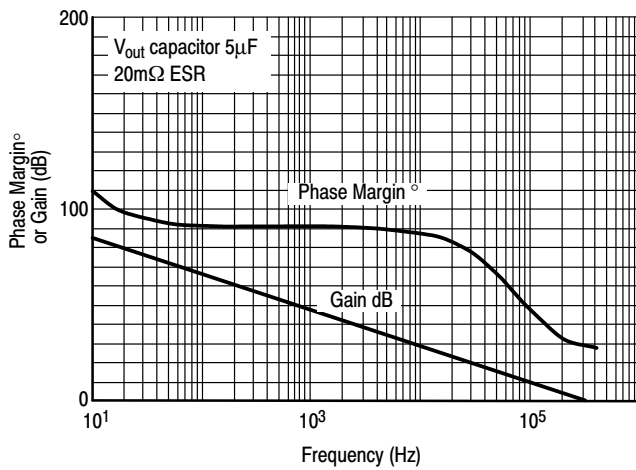
Figure 4. 5.0 V Detect Thresholds Diagram



## NOTE:

(1)  $V_{in}$  rise and fall times (10% to 90%) to be  $\leq 100 ns$ .

Figure 5. Timing Diagram



NOTE:  $V_{out}$  capacitor  $\geq 4.7 \mu F$  over operating temperature range.  
Maximum ESR permissible = 500 mΩ over operating temperature range.

Figure 6. Predicted Gain and Phase at Zero Load Current

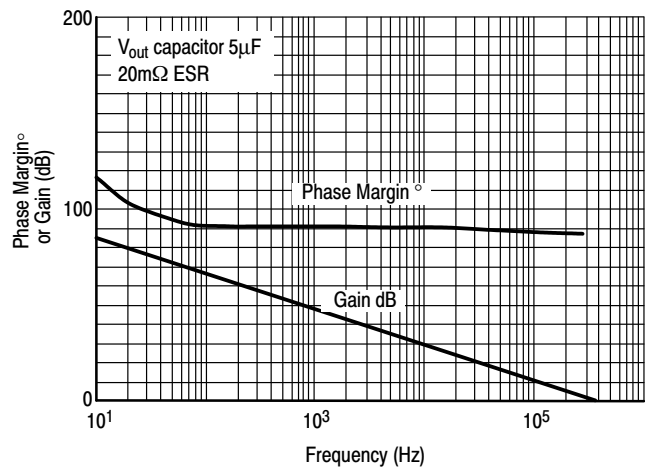
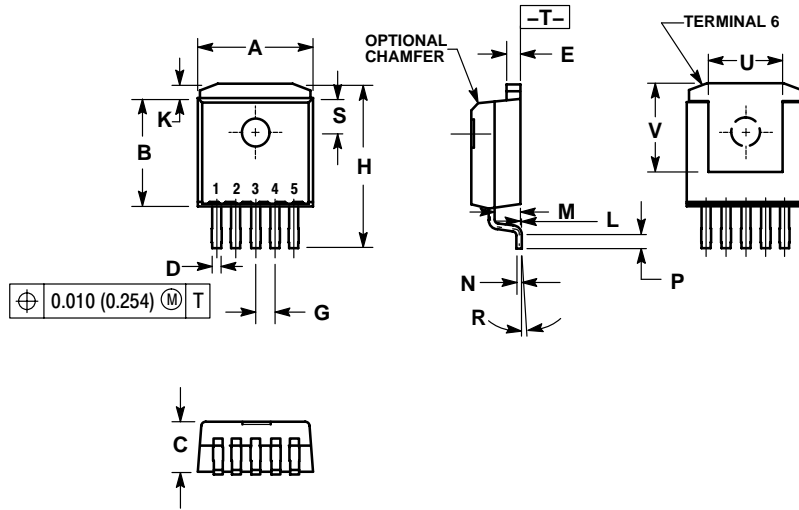


Figure 7. Predicted Gain and Phase at Full Load Current

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## PACKAGE DIMENSIONS


(D<sup>2</sup>PAK)  
D2T SUFFIX  
PLASTIC PACKAGE  
CASE 936A-02  
ISSUE B



### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS A AND K.
4. DIMENSIONS U AND V ESTABLISH A MINIMUM MOUNTING SURFACE FOR TERMINAL 6.
5. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.386	0.403	9.804	10.236
B	0.356	0.368	9.042	9.347
C	0.170	0.180	4.318	4.572
D	0.026	0.036	0.660	0.914
E	0.045	0.055	1.143	1.397
G	0.067 BSC		1.702 BSC	
H	0.539	0.579	13.691	14.707
K	0.050 REF		1.270 REF	
L	0.000	0.010	0.000	0.254
M	0.088	0.102	2.235	2.591
N	0.018	0.026	0.457	0.660
P	0.058	0.078	1.473	1.981
R	5° REF		5° REF	
S	0.116 REF		2.946 REF	
U	0.200 MIN		5.080 MIN	
V	0.250 MIN		6.350 MIN	

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